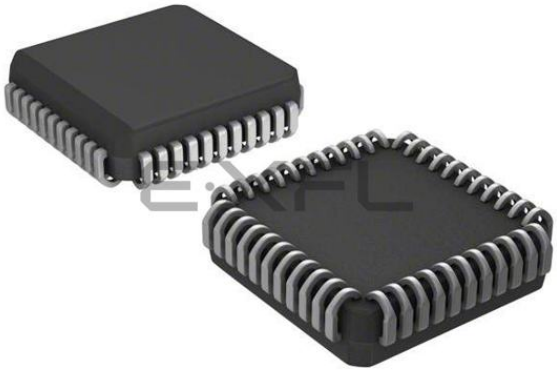

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What is "Embedded - Microcontrollers"?

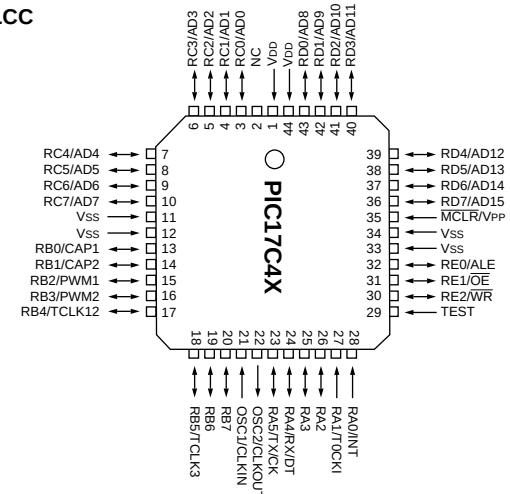
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

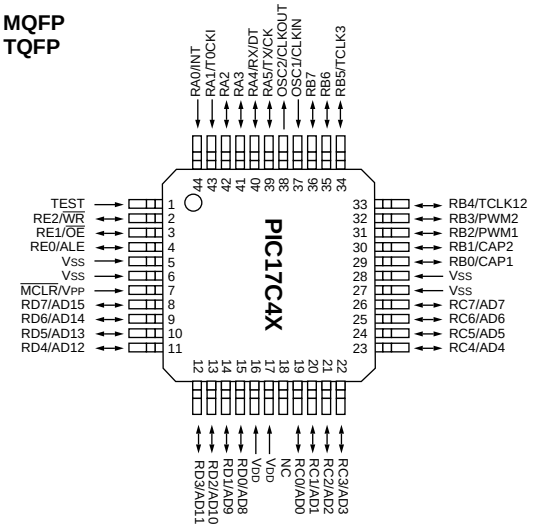
Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	25MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	4KB (2K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	232 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c42at-25e-l

Pin Diagrams Cont.'d

PLCC



MQFP
TQFP



All devices are available in all package types, listed in Section 21.0, with the following exceptions:

- ROM devices are not available in Windowed CERDIP Packages
- TQFP is not available for the PIC17C42.

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, and the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 3-3.

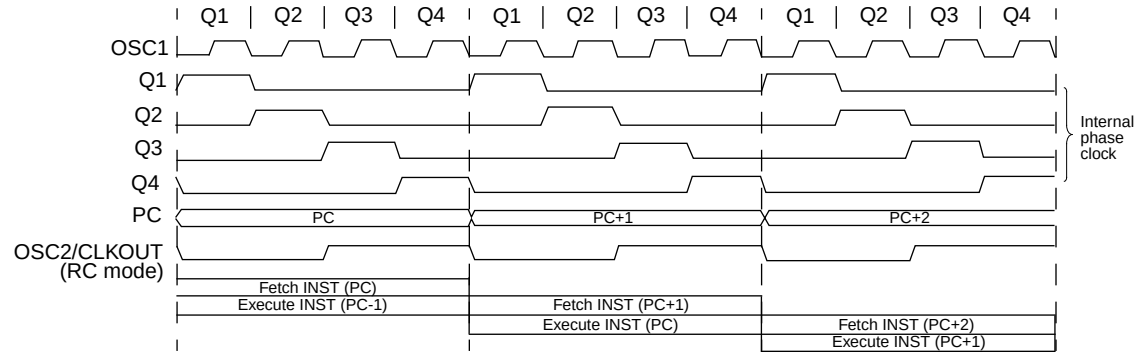
3.2 Instruction Flow/Pipelining

An “Instruction Cycle” consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. `GOTO`) then two cycles are required to complete the instruction (Example 3-2).

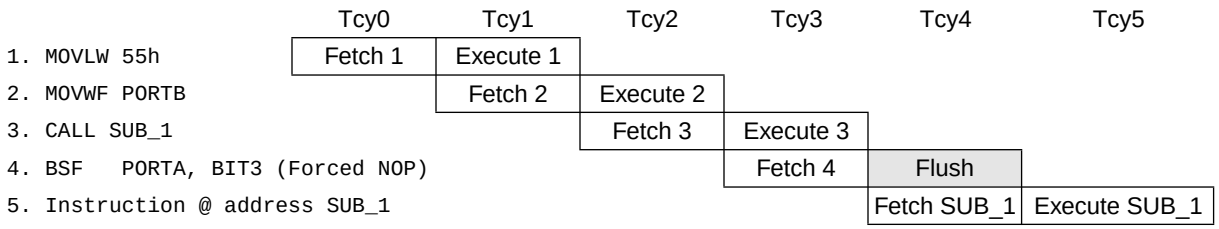
A fetch cycle begins with the program counter incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the “Instruction Register (IR)” in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-3: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-2: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

5.1 Interrupt Status Register (INTSTA)

The Interrupt Status/Control register (INTSTA) records the individual interrupt requests in flag bits, and contains the individual interrupt enable bits (not for the peripherals).

The PEIF bit is a read only, bit wise OR of all the peripheral flag bits in the PIR register (Figure 5-4).

Note:	T0IF, INTF, T0CKIF, or PEIF will be set by the specified condition, even if the corresponding interrupt enable bit is clear (interrupt disabled) or the GLINTD bit is set (all interrupts disabled).

Care should be taken when clearing any of the INTSTA register enable bits when interrupts are enabled (GLINTD is clear). If any of the INTSTA flag bits (T0IF, INTF, T0CKIF, or PEIF) are set in the same instruction cycle as the corresponding interrupt enable bit is cleared, the device will vector to the reset address (0x00).

When disabling any of the INTSTA enable bits, the GLINTD bit should be set (disabled).

FIGURE 5-2: INTSTA REGISTER (ADDRESS: 07h, UNBANKED)

R - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0	R/W - 0
PEIF	T0CKIF	T0IF	INTF	PEIE	T0CKIE	T0IE	INTE
bit7							bit0

R = Readable bit
W = Writable bit
- n = Value at POR reset

bit 7: **PEIF**: Peripheral Interrupt Flag bit
This bit is the OR of all peripheral interrupt flag bits AND'ed with their corresponding enable bits.
1 = A peripheral interrupt is pending
0 = No peripheral interrupt is pending

bit 6: **T0CKIF**: External Interrupt on T0CKI Pin Flag bit
This bit is cleared by hardware, when the interrupt logic forces program execution to vector (18h).
1 = The software specified edge occurred on the RA1/T0CKI pin
0 = The software specified edge did not occur on the RA1/T0CKI pin

bit 5: **T0IF**: TMR0 Overflow Interrupt Flag bit
This bit is cleared by hardware, when the interrupt logic forces program execution to vector (10h).
1 = TMR0 overflowed
0 = TMR0 did not overflow

bit 4: **INTF**: External Interrupt on INT Pin Flag bit
This bit is cleared by hardware, when the interrupt logic forces program execution to vector (08h).
1 = The software specified edge occurred on the RA0/INT pin
0 = The software specified edge did not occur on the RA0/INT pin

bit 3: **PEIE**: Peripheral Interrupt Enable bit
This bit enables all peripheral interrupts that have their corresponding enable bits set.
1 = Enable peripheral interrupts
0 = Disable peripheral interrupts

bit 2: **T0CKIE**: External Interrupt on T0CKI Pin Enable bit
1 = Enable software specified edge interrupt on the RA1/T0CKI pin
0 = Disable interrupt on the RA1/T0CKI pin

bit 1: **T0IE**: TMR0 Overflow Interrupt Enable bit
1 = Enable TMR0 overflow interrupt
0 = Disable TMR0 overflow interrupt

bit 0: **INTE**: External Interrupt on RA0/INT Pin Enable bit
1 = Enable software specified edge interrupt on the RA0/INT pin
0 = Disable software specified edge interrupt on the RA0/INT pin

NOTES:

6.2 Data Memory Organization

Data memory is partitioned into two areas. The first is the General Purpose Registers (GPR) area, while the second is the Special Function Registers (SFR) area. The SFRs control the operation of the device.

Portions of data memory are banked, this is for both areas. The GPR area is banked to allow greater than 232 bytes of general purpose RAM. SFRs are for the registers that control the peripheral functions. Banking requires the use of control bits for bank selection. These control bits are located in the Bank Select Register (BSR). If an access is made to a location outside this banked region, the BSR bits are ignored. Figure 6-5 shows the data memory map organization for the PIC17C42 and Figure 6-6 for all of the other PIC17C4X devices.

Instructions MOVPF and MOVFP provide the means to move values from the peripheral area (“P”) to any location in the register file (“F”), and vice-versa. The definition of the “P” range is from 0h to 1Fh, while the “F” range is 0h to FFh. The “P” range has six more locations than peripheral registers (eight locations for the PIC17C42 device) which can be used as General Purpose Registers. This can be useful in some applications where variables need to be copied to other locations in the general purpose RAM (such as saving status information during an interrupt).

The entire data memory can be accessed either directly or indirectly through file select registers FSR0 and FSR1 (Section 6.4). Indirect addressing uses the appropriate control bits of the BSR for accesses into the banked areas of data memory. The BSR is explained in greater detail in Section 6.8.

6.2.1 GENERAL PURPOSE REGISTER (GPR)

All devices have some amount of GPR area. The GPRs are 8-bits wide. When the GPR area is greater than 232, it must be banked to allow access to the additional memory space.

Only the PIC17C43 and PIC17C44 devices have banked memory in the GPR area. To facilitate switching between these banks, the MOVLR bank instruction has been added to the instruction set. GPRs are not initialized by a Power-on Reset and are unchanged on all other resets.

6.2.2 SPECIAL FUNCTION REGISTERS (SFR)

The SFRs are used by the CPU and peripheral functions to control the operation of the device (Figure 6-5 and Figure 6-6). These registers are static RAM.

The SFRs can be classified into two sets, those associated with the “core” function and those related to the peripheral functions. Those registers related to the “core” are described here, while those related to a peripheral feature are described in the section for each peripheral feature.

The peripheral registers are in the banked portion of memory, while the core registers are in the unbanked region. To facilitate switching between the peripheral banks, the MOVLB bank instruction has been provided.

NOTES:

TABLE 9-7: PORTD FUNCTIONS

Name	Bit	Buffer Type	Function
RD0/AD8	bit0	TTL	Input/Output or system bus address/data pin.
RD1/AD9	bit1	TTL	Input/Output or system bus address/data pin.
RD2/AD10	bit2	TTL	Input/Output or system bus address/data pin.
RD3/AD11	bit3	TTL	Input/Output or system bus address/data pin.
RD4/AD12	bit4	TTL	Input/Output or system bus address/data pin.
RD5/AD13	bit5	TTL	Input/Output or system bus address/data pin.
RD6/AD14	bit6	TTL	Input/Output or system bus address/data pin.
RD7/AD15	bit7	TTL	Input/Output or system bus address/data pin.

Legend: TTL = TTL input.

TABLE 9-8: REGISTERS/BITS ASSOCIATED WITH PORTD

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
13h, Bank 1	PORTD	RD7/ AD15	RD6/ AD14	RD5/ AD13	RD4/ AD12	RD3/ AD11	RD2/ AD10	RD1/ AD9	RD0/ AD8	xxxx xxxx	uuuu uuuu
12h, Bank 1	DDRD	Data direction register for PORTD								1111 1111	1111 1111

Legend: x = unknown, u = unchanged.

Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and the Watchdog Timer Reset.

11.1 Timer0 Operation

When the T0CS (T0STA<5>) bit is set, TMR0 increments on the internal clock. When T0CS is clear, TMR0 increments on the external clock (RA1/T0CKI pin). The external clock edge can be configured in software. When the T0SE (T0STA<6>) bit is set, the timer will increment on the rising edge of the RA1/T0CKI pin. When T0SE is clear, the timer will increment on the falling edge of the RA1/T0CKI pin. The prescaler can be programmed to introduce a prescale of 1:1 to 1:256. The timer increments from 0000h to FFFFh and rolls over to 0000h. On overflow, the TMR0 Interrupt Flag bit (T0IF) is set. The TMR0 interrupt can be masked by clearing the corresponding TMR0 Interrupt Enable bit (T0IE). The TMR0 Interrupt Flag bit (T0IF) is automatically cleared when vectoring to the TMR0 interrupt vector.

11.2 Using Timer0 with External Clock

When the external clock input is used for Timer0, it is synchronized with the internal phase clocks. Figure 11-3 shows the synchronization of the external clock. This synchronization is done after the prescaler. The output of the prescaler (PSOUT) is sampled twice in every instruction cycle to detect a rising or a falling edge. The timing requirements for the external clock are detailed in the electrical specification section for the desired device.

11.2.1 DELAY FROM EXTERNAL CLOCK EDGE

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time TMR0 is actually incremented. Figure 11-3 shows that this delay is between 3TOSC and 7TOSC. Thus, for example, measuring the interval between two edges (e.g. period) will be accurate within ±4TOSC (±121 ns @ 33 MHz).

FIGURE 11-2: TIMER0 MODULE BLOCK DIAGRAM

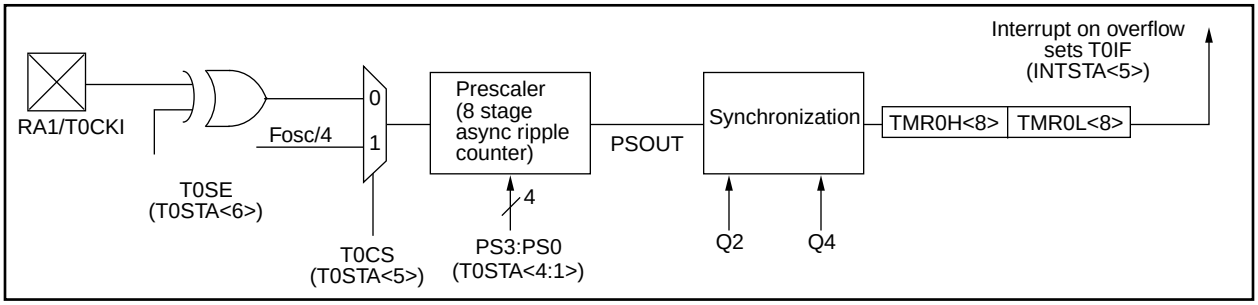
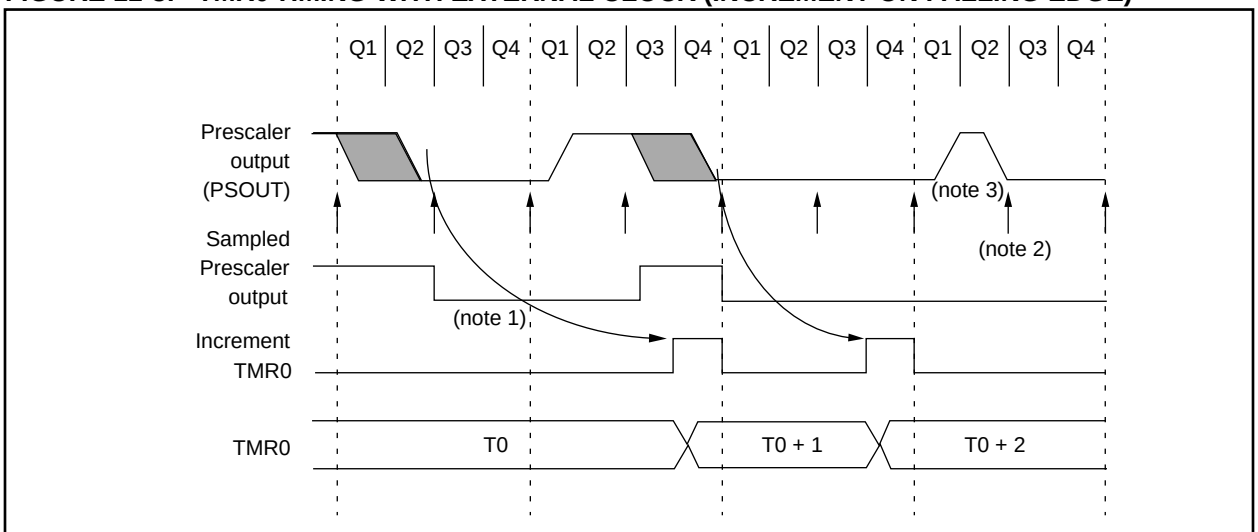


FIGURE 11-3: TMR0 TIMING WITH EXTERNAL CLOCK (INCREMENT ON FALLING EDGE)



Note 1: The delay from the T0CKI edge to the TMR0 increment is 3Tosc to 7Tosc.
2: ↑ = PSOUT is sampled here.
3: The PSOUT high time is too short and is missed by the sampling circuit.

15.2 Q Cycle Activity

Each instruction cycle (Tcy) is comprised of four Q cycles (Q1-Q4). The Q cycles provide the timing/designation for the Decode, Read, Execute, Write etc., of each instruction cycle. The following diagram shows the relationship of the Q cycles to the instruction cycle.

The 4 Q cycles that make up an instruction cycle (Tcy) can be generalized as:

Q1: Instruction Decode Cycle or forced NOP

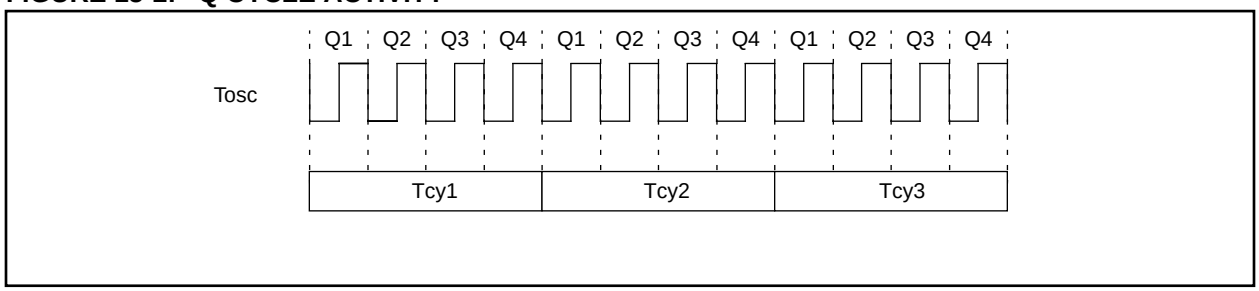
Q2: Instruction Read Cycle or NOP

Q3: Instruction Execute

Q4: Instruction Write Cycle or NOP

Each instruction will show the detailed Q cycle operation for the instruction.

FIGURE 15-2: Q CYCLE ACTIVITY



IORWF **Inclusive OR WREG with f**

Syntax: [*label*] IORWF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: (WREG) .OR. (f) → (dest)

Status Affected: Z

Encoding:

0000	100d	ffff	ffff

Description: Inclusive OR WREG with register 'f'. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example:
```
IORWF  RESULT, 0
```
Before Instruction
RESULT = 0x13
WREG = 0x91

After Instruction
RESULT = 0x13
WREG = 0x93

LCALL **Long Call**

Syntax: [*label*] LCALL k

Operands: $0 \le k \le 255$

Operation: PC + 1 → TOS;
k → PCL, (PCLATH) → PCH

Status Affected: None

Encoding:

1011	0111	kkkk	kkkk

Description: LCALL allows an unconditional subroutine call to anywhere within the 64k program memory space.

First, the return address (PC + 1) is pushed onto the stack. A 16-bit destination address is then loaded into the program counter. The lower 8-bits of the destination address is embedded in the instruction. The upper 8-bits of PC is loaded from PC high holding latch, PCLATH.

Words: 1

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Execute	Write register PCL
Forced NOP	NOP	Execute	NOP

Example:
```
MOVLW  HIGH(SUBROUTINE)
MOVPF  WREG, PCLATH
LCALL  LOW(SUBROUTINE)
```
Before Instruction
SUBROUTINE = 16-bit Address
PC = ?

After Instruction
PC = Address (SUBROUTINE)

RLNCF **Rotate Left f (no carry)**

Syntax: [*label*] RLNCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

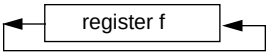
Operation: f<n> → d<n+1>;
f<7> → d<0>

Status Affected: None

Encoding:

0010	001d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the left. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is stored back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RLNCF REG, 1

Before Instruction
C = 0
REG = 1110 1011

After Instruction
C =
REG = 1101 0111

RRCF **Rotate Right f through Carry**

Syntax: [*label*] RRCF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

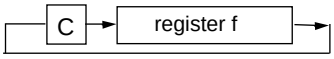
Operation: f<n> → d<n-1>;
f<0> → C;
C → d<7>

Status Affected: C

Encoding:

0001	100d	ffff	ffff

Description: The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.



Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: RRCF REG1,0

Before Instruction
REG1 = 1110 0110
C = 0

After Instruction
REG1 = 1110 0110
WREG = 0111 0011
C = 0

SWAPF **Swap f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 255$
$d \in [0,1]$

Operation: f<3:0> → dest<7:4>;
f<7:4> → dest<3:0>

Status Affected: None

Encoding:

0001	110d	ffff	ffff

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example: `SWAPF REG, 0`

Before Instruction
REG = 0x53

After Instruction
REG = 0x35

TABLRD **Table Read**

Syntax: [*label*] TABLRD t,i,f

Operands: $0 \le f \le 255$
$i \in [0,1]$
$t \in [0,1]$

Operation: If t = 1,
TBLATH → f;
If t = 0,
TBLATL → f;
Prog Mem (TBLPTR) → TBLAT;
If i = 1,
TBLPTR + 1 → TBLPTR

Status Affected: None

Encoding:

1010	10ti	ffff	ffff

Description:
1. A byte of the table latch (TBLAT) is moved to register file 'f'.
If t = 0: the high byte is moved;
If t = 1: the low byte is moved
2. Then the contents of the program memory location pointed to by the 16-bit Table Pointer (TBLPTR) is loaded into the 16-bit Table Latch (TBLAT).
3. If i = 1: TBLPTR is incremented;
If i = 0: TBLPTR is not incremented

Words: 1

Cycles: 2 (3 cycle if f = PCL)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register TBLATH or TBLATL	Execute	Write register 'f'

Applicable Devices	42	R42	42A	43	R43	44

DC CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)
Operating temperature
-40°C ≤ TA ≤ +85°C for industrial and
0°C ≤ TA ≤ +70°C for commercial
Operating voltage VDD range as described in Section 17.1

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
		Output Low Voltage					
D080	VOL	I/O ports (except RA2 and RA3)	–	–	0.1VDD	V	IOL = 4 mA
D081		with TTL buffer	–	–	0.4	V	IOL = 6 mA, VDD = 4.5V Note 6
D082		RA2 and RA3	–	–	3.0	V	IOL = 60.0 mA, VDD = 5.5V
D083		OSC2/CLKOUT (RC and EC osc modes)	–	–	0.4	V	IOL = 2 mA, VDD = 4.5V
		Output High Voltage (Note 3)					
D090	VOH	I/O ports (except RA2 and RA3)	0.9VDD	–	–	V	IOH = -2 mA
D091		with TTL buffer	2.4	–	–	V	IOH = -6.0 mA, VDD = 4.5V Note 6
D092		RA2 and RA3	–	–	12	V	Pulled-up to externally applied voltage
D093		OSC2/CLKOUT (RC and EC osc modes)	2.4	–	–	V	IOH = -5 mA, VDD = 4.5V
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	–	–	25 ††	pF	In EC or RC osc modes when OSC2 pin is outputting CLKOUT. External clock is used to drive OSC1.
D101	CIO	All I/O pins and OSC2 (in RC mode)	–	–	50 ††	pF	
D102	CAD	System Interface Bus (PORTC, PORTD and PORTE)	–	–	100 ††	pF	In Microprocessor or Extended Microcontroller mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

†† Design guidance to attain the AC timing specifications. These loads are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{MCLR}$/Vpp pin may be kept in this range at times other than programming, but this is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-19: V_{TH}, V_{IL} of I/O PINS (SCHMITT TRIGGER) vs. V_{DD}

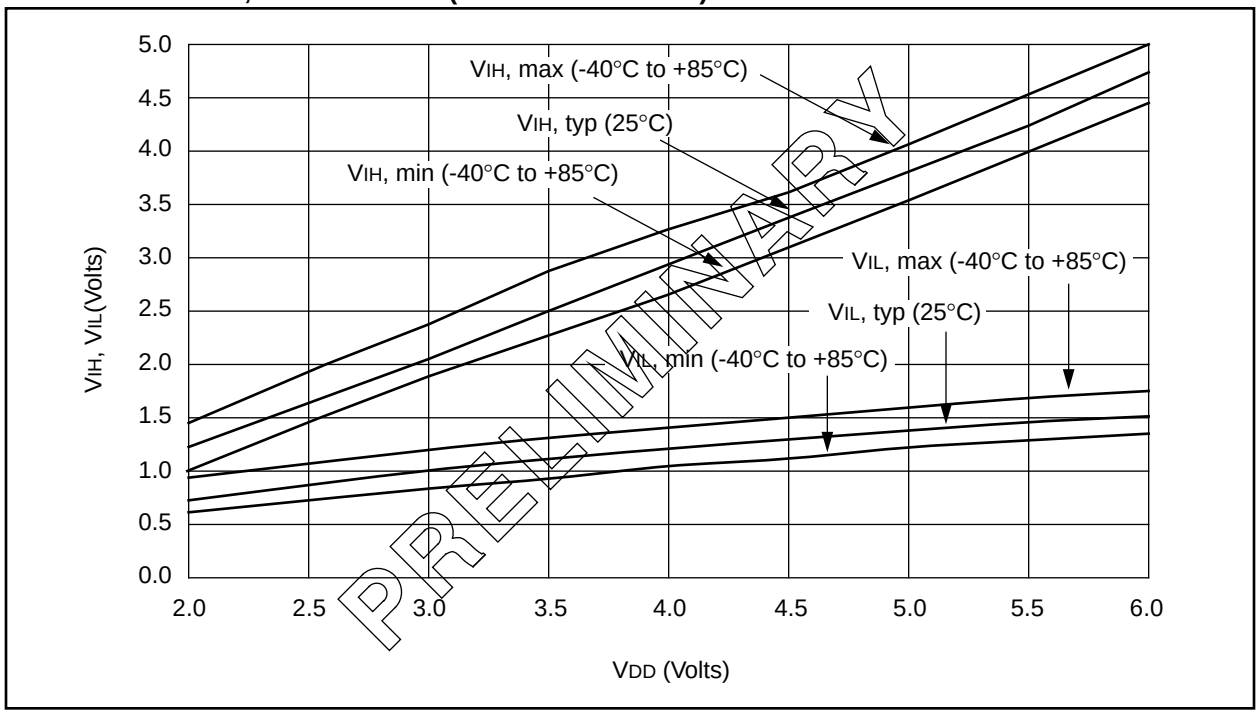
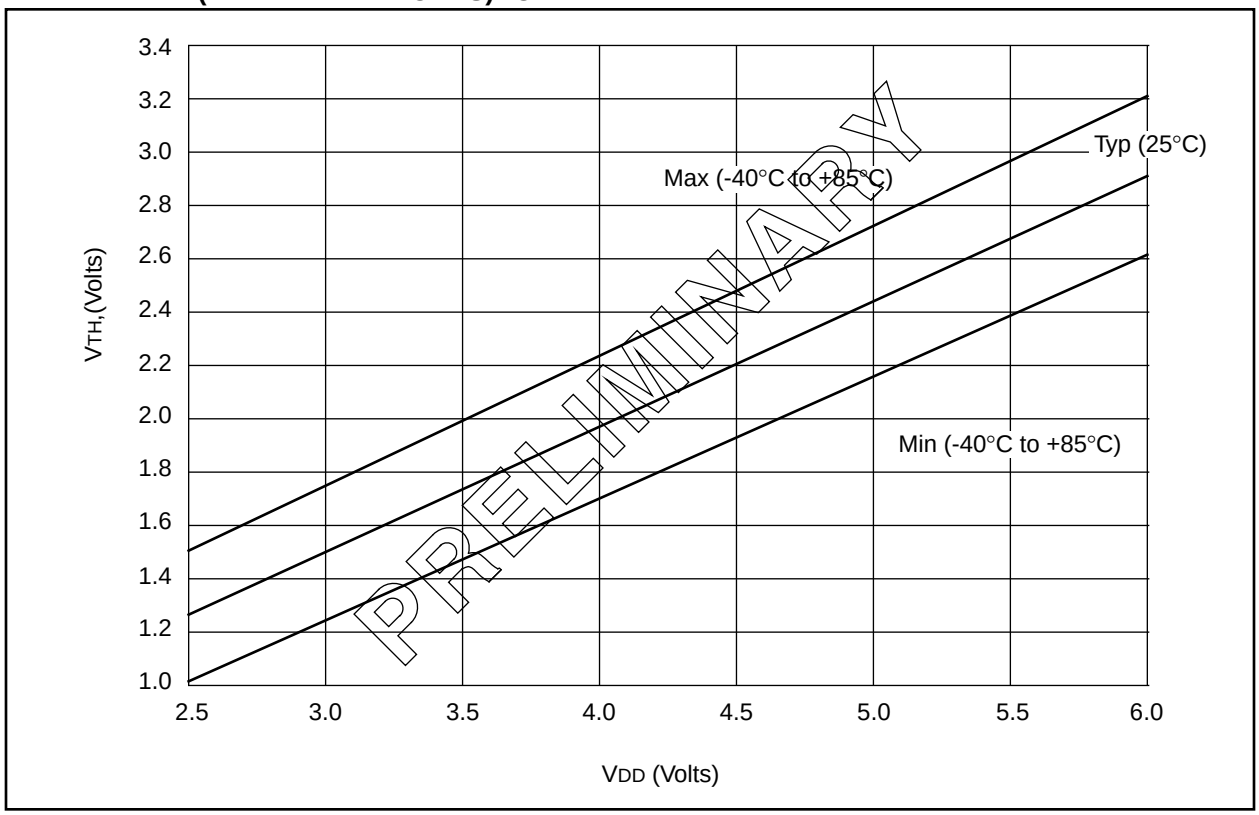


FIGURE 18-20: V_{TH} (INPUT THRESHOLD VOLTAGE) OF OSC1 INPUT (IN XT AND LF MODES) vs. V_{DD}



Applicable Devices	42	R42	42A	43	R43	44

19.3 DC CHARACTERISTICS: PIC17CR42/42A/43/R43/44-16 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-25 (Commercial, Industrial) PIC17CR42/42A/43/R43/44-33 (Commercial, Industrial) PIC17LCR42/42A/43/R43/44-08 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in Section 19.1				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
		Input Low Voltage					
	VIL	I/O ports					
D030		with TTL buffer	VSS	–	0.8	V	4.5V ≤ VDD ≤ 5.5V
			VSS	–	0.2VDD	V	2.5V ≤ VDD ≤ 4.5V
D031		with Schmitt Trigger buffer	VSS	–	0.2VDD	V	
D032		$\overline{MCLR}$, OSC1 (in EC and RC mode)	Vss	–	0.2VDD	V	Note1
D033		OSC1 (in XT, and LF mode)	–	0.5VDD	–	V	
		Input High Voltage					
	VIH	I/O ports					
D040		with TTL buffer	2.0	–	VDD	V	4.5V ≤ VDD ≤ 5.5V
			1 + 0.2VDD	–	VDD	V	2.5V ≤ VDD ≤ 4.5V
D041		with Schmitt Trigger buffer	0.8VDD	–	VDD	V	
D042		$\overline{MCLR}$	0.8VDD	–	VDD	V	Note1
D043		OSC1 (XT, and LF mode)	–	0.5VDD	–	V	
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15VDD *	–	–	V	
		Input Leakage Current (Notes 2, 3)					
D060	IIL	I/O ports (except RA2, RA3)	–	–	±1	µA	Vss ≤ VPIN ≤ VDD, I/O Pin at hi-impedance PORTB weak pull-ups disabled
D061		$\overline{MCLR}$	–	–	±2	µA	VPIN = Vss or VPIN = VDD
D062		RA2, RA3			±2	µA	Vss ≤ VRA2, VRA3 ≤ 12V
D063		OSC1, TEST (EC, RC modes)	–	–	±1	µA	Vss ≤ VPIN ≤ VDD
D063B		OSC1, TEST (XT, LF modes)	–	–	VPIN	µA	RF ≥ 1 MΩ, see Figure 14.2
D064		$\overline{MCLR}$	–	–	10	µA	VMCLR = VPP = 12V (when not programming)
D070	IPURB	PORTB weak pull-up current	60	200	400	µA	VPIN = VSS, $\overline{RBPU}$ = 0 4.5V ≤ VDD ≤ 6.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{MCLR}$/VPP pin may be kept in this range at times other than programming, but is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-11: MEMORY INTERFACE WRITE TIMING (NOT SUPPORTED IN PIC17LC4X DEVICES)

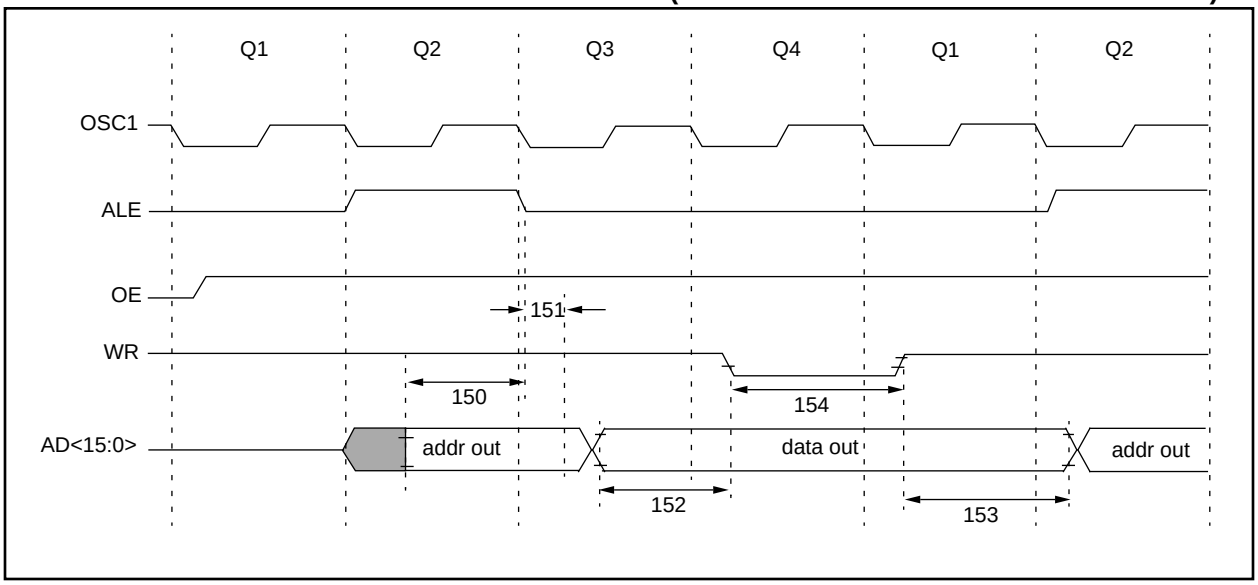


TABLE 19-11: MEMORY INTERFACE WRITE REQUIREMENTS (NOT SUPPORTED IN PIC17LC4X DEVICES)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25Tcy - 10	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
152	TadV2wrL	Data out valid to $\overline{WR}$↓ (data setup time)	0.25Tcy - 40	—	—	ns	
153	TwrH2adI	$\overline{WR}$↑ to data out invalid (data hold time)	—	0.25TCY §	—	ns	
154	TwrL	$\overline{WR}$ pulse width	—	0.25TCY §	—	ns	

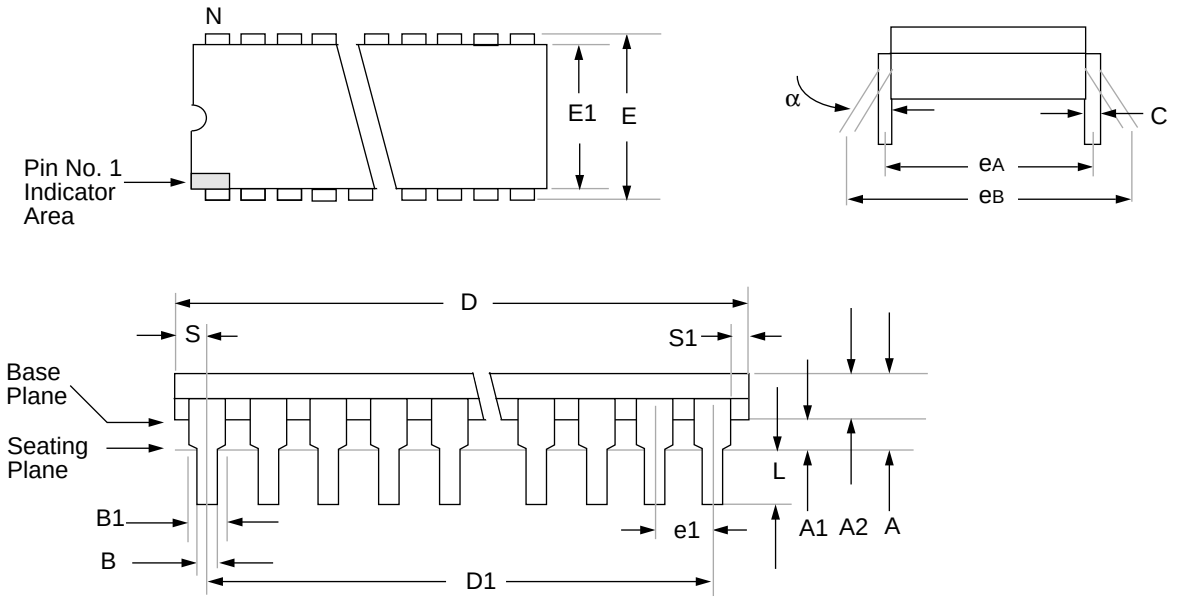
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

NOTES:

21.2 40-Lead Plastic Dual In-line (600 mil)



Package Group: Plastic Dual In-Line (PLA)						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	–	5.080		–	0.200	
A1	0.381	–		0.015	–	
A2	3.175	4.064		0.125	0.160	
B	0.355	0.559		0.014	0.022	
B1	1.270	1.778	**Typical**	0.050	0.070	**Typical**
C	0.203	0.381	**Typical**	0.008	0.015	**Typical**
D	51.181	52.197		2.015	2.055	
D1	48.260	48.260	**Reference**	1.900	1.900	**Reference**
E	15.240	15.875		0.600	0.625	
E1	13.462	13.970		0.530	0.550	
e1	2.489	2.591	**Typical**	0.098	0.102	**Typical**
eA	15.240	15.240	**Reference**	0.600	0.600	**Reference**
eB	15.240	17.272		0.600	0.680	
L	2.921	3.683		0.115	0.145	
N	40	40		40	40	
S	1.270	–		0.050	–	
S1	0.508	–		0.020	–	

NOTES:

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